

Claims

1. A method for reducing nanoscale roughness on a surface, comprising the step of exposing the surface to an environment for promoting evaporation of molecules or atoms from one or more angular features of said surface, whereby said nanoscale roughness is reduced.
2. The method of claim 1 wherein said step for promoting evaporation comprises heating said surface.
3. The method of claim 1 wherein said step of exposing the surface to an environment for promoting evaporation comprises reducing a vapor pressure exerted by said molecules or atoms in said environment.
4. The method of claim 3 wherein said step of reducing a vapor pressure comprises evacuating said environment.
5. The method of claim 3 wherein said step of reducing a vapor pressure comprises purging said environment with an inert gas.
6. The method of claim 3 wherein said step of reducing a vapor pressure comprises the combination of an evacuating step and a purging step.
7. The method of claim 1 wherein said step for promoting evaporation comprises the combination of heating said surface and reducing a vapor pressure exerted by said molecules or atoms in said environment
8. The method of claim 3 wherein said step of reducing a vapor pressure comprises evacuating said environment.
9. The method of claim 3 wherein said step of reducing a vapor pressure comprises purging said environment with an inert gas.
10. The method of claim 3 wherein said step of reducing a vapor pressure comprises the combination of an evacuating step and a purging step.
11. A method for reducing nanoscale roughness on a pair of surfaces, comprising the step of exposing the surfaces to an environment for promoting evaporation of molecules or atoms from one or more angular features of said surfaces, whereby said nanoscale roughness is reduced.
12. The method of claim 11 wherein said step for promoting evaporation comprises heating said surfaces.
13. The method of claim 11 wherein said step of exposing the surfaces to an environment for promoting evaporation comprises reducing a

vapor pressure exerted by said molecules or atoms in said environment.

14. The method of claim 13 wherein said step of reducing a vapor pressure comprises evacuating said environment.
15. The method of claim 13 wherein said step of reducing a vapor pressure comprises purging said environment with an inert gas.
16. The method of claim 13 wherein said step of reducing a vapor pressure comprises the combination of an evacuating step and a purging step.
17. The method of claim 11 wherein said step for promoting evaporation comprises the combination of heating said surfaces and reducing a vapor pressure exerted by said molecules or atoms in said environment
18. The method of claim 17 wherein said step of reducing a vapor pressure comprises evacuating said environment.
19. The method of claim 17 wherein said step of reducing a vapor pressure comprises purging said environment with an inert gas.
20. The method of claim 17 wherein said step of reducing a vapor pressure comprises the combination of an evacuating step and a purging step.
21. The method of claim 11 wherein said step for promoting evaporation comprises applying a potential difference between said surfaces.
22. The method of claim 11 wherein said step for promoting evaporation comprises operating said pair of surfaces as electrodes in a diode device.